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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	8KB (4K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic17c43-33i-p">https://www.e-xfl.com/product-detail/microchip-technology/pic17c43-33i-p</a>

## 5.5 RA0/INT Interrupt

The external interrupt on the RA0/INT pin is edge triggered. Either the rising edge, if INTEDG bit (T0STA<7>) is set, or the falling edge, if INTEDG bit is clear. When a valid edge appears on the RA0/INT pin, the INTF bit (INTSTA<4>) is set. This interrupt can be disabled by clearing the INTE control bit (INTSTA<0>). The INT interrupt can wake the processor from SLEEP. See Section 14.4 for details on SLEEP operation.

## 5.6 TMR0 Interrupt

An overflow (FFFFh → 0000h) in TMR0 will set the T0IF (INTSTA<5>) bit. The interrupt can be enabled/disabled by setting/clearing the T0IE control bit (INTSTA<1>). For operation of the Timer0 module, see Section 11.0.

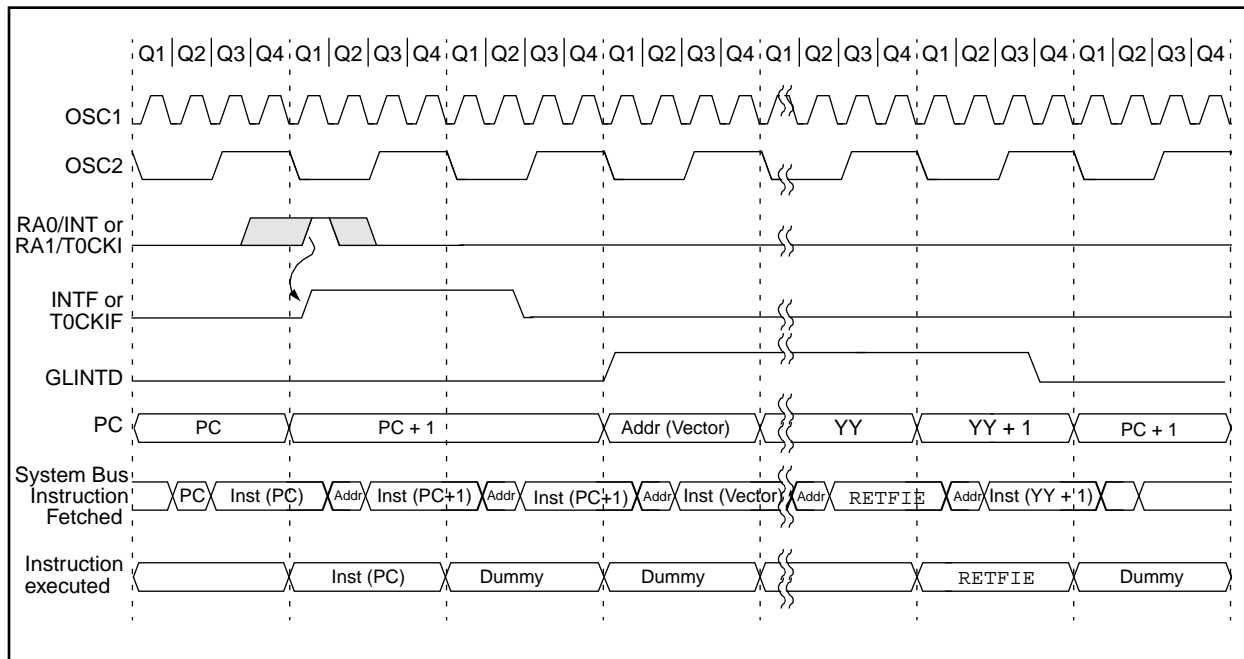
## 5.7 T0CKI Interrupt

The external interrupt on the RA1/T0CKI pin is edge triggered. Either the rising edge, if the T0SE bit (T0STA<6>) is set, or the falling edge, if the T0SE bit is clear. When a valid edge appears on the RA1/T0CKI pin, the T0CKIF bit (INTSTA<6>) is set. This interrupt can be disabled by clearing the T0CKIE control bit (INTSTA<2>). The T0CKI interrupt can wake up the processor from SLEEP. See Section 14.4 for details on SLEEP operation.

## 5.8 Peripheral Interrupt

The peripheral interrupt flag indicates that at least one of the peripheral interrupts occurred (PEIF is set). The PEIF bit is a read only bit, and is a bit wise OR of all the flag bits in the PIR register AND'ed with the corresponding enable bits in the PIE register. Some of the peripheral interrupts can wake the processor from SLEEP. See Section 14.4 for details on SLEEP operation.

**FIGURE 5-5: INT PIN / T0CKI PIN INTERRUPT TIMING**



## 6.2 Data Memory Organization

Data memory is partitioned into two areas. The first is the General Purpose Registers (GPR) area, while the second is the Special Function Registers (SFR) area. The SFRs control the operation of the device.

Portions of data memory are banked, this is for both areas. The GPR area is banked to allow greater than 232 bytes of general purpose RAM. SFRs are for the registers that control the peripheral functions. Banking requires the use of control bits for bank selection. These control bits are located in the Bank Select Register (BSR). If an access is made to a location outside this banked region, the BSR bits are ignored. Figure 6-5 shows the data memory map organization for the PIC17C42 and Figure 6-6 for all of the other PIC17C4X devices.

Instructions `MOVPF` and `MOVFP` provide the means to move values from the peripheral area ("P") to any location in the register file ("F"), and vice-versa. The definition of the "P" range is from 0h to 1Fh, while the "F" range is 0h to FFh. The "P" range has six more locations than peripheral registers (eight locations for the PIC17C42 device) which can be used as General Purpose Registers. This can be useful in some applications where variables need to be copied to other locations in the general purpose RAM (such as saving status information during an interrupt).

The entire data memory can be accessed either directly or indirectly through file select registers FSR0 and FSR1 (Section 6.4). Indirect addressing uses the appropriate control bits of the BSR for accesses into the banked areas of data memory. The BSR is explained in greater detail in Section 6.8.

### 6.2.1 GENERAL PURPOSE REGISTER (GPR)

All devices have some amount of GPR area. The GPRs are 8-bits wide. When the GPR area is greater than 232, it must be banked to allow access to the additional memory space.

Only the PIC17C43 and PIC17C44 devices have banked memory in the GPR area. To facilitate switching between these banks, the `MOVLB` bank instruction has been added to the instruction set. GPRs are not initialized by a Power-on Reset and are unchanged on all other resets.

### 6.2.2 SPECIAL FUNCTION REGISTERS (SFR)

The SFRs are used by the CPU and peripheral functions to control the operation of the device (Figure 6-5 and Figure 6-6). These registers are static RAM.

The SFRs can be classified into two sets, those associated with the "core" function and those related to the peripheral functions. Those registers related to the "core" are described here, while those related to a peripheral feature are described in the section for each peripheral feature.

The peripheral registers are in the banked portion of memory, while the core registers are in the unbanked region. To facilitate switching between the peripheral banks, the `MOVLB` bank instruction has been provided.

## 6.4.1 INDIRECT ADDRESSING REGISTERS

The PIC17C4X has four registers for indirect addressing. These registers are:

- INDF0 and FSR0
- INDF1 and FSR1

Registers INDF0 and INDF1 are not physically implemented. Reading or writing to these registers activates indirect addressing, with the value in the corresponding FSR register being the address of the data. The FSR is an 8-bit register and allows addressing anywhere in the 256-byte data memory address range. For banked memory, the bank of memory accessed is specified by the value in the BSR.

If file INDF0 (or INDF1) itself is read indirectly via an FSR, all '0's are read (Zero bit is set). Similarly, if INDF0 (or INDF1) is written to indirectly, the operation will be equivalent to a NOP, and the status bits are not affected.

## 6.4.2 INDIRECT ADDRESSING OPERATION

The indirect addressing capability has been enhanced over that of the PIC16CXX family. There are two control bits associated with each FSR register. These two bits configure the FSR register to:

- Auto-decrement the value (address) in the FSR after an indirect access
- Auto-increment the value (address) in the FSR after an indirect access
- No change to the value (address) in the FSR after an indirect access

These control bits are located in the ALUSTA register. The FSR1 register is controlled by the FS3:FS2 bits and FSR0 is controlled by the FS1:FS0 bits.

When using the auto-increment or auto-decrement features, the effect on the FSR is not reflected in the ALUSTA register. For example, if the indirect address causes the FSR to equal '0', the Z bit will not be set.

If the FSR register contains a value of 0h, an indirect read will read 0h (Zero bit is set) while an indirect write will be equivalent to a NOP (status bits are not affected).

Indirect addressing allows single cycle data transfers within the entire data space. This is possible with the use of the MOVPPF and MOVFP instructions, where either 'p' or 'f' is specified as INDF0 (or INDF1).

If the source or destination of the indirect address is in banked memory, the location accessed will be determined by the value in the BSR.

A simple program to clear RAM from 20h - FFh is shown in Example 6-1.

### EXAMPLE 6-1: INDIRECT ADDRESSING

```
MOVLW    0x20      ;
MOVWF    FSR0      ; FSR0 = 20h
BCF      ALUSTA, FS1 ; Increment FSR
BSF      ALUSTA, FS0 ; after access
BCF      ALUSTA, C   ; C = 0
MOVLW    END_RAM + 1 ;
LP CLRf    INDF0      ; Addr(FSR) = 0
CPFSEQ   FSR0        ; FSR0 = END_RAM+1?
GOTO     LP          ; NO, clear next
:         ; YES, All RAM is
:         ; cleared
```

## 6.5 Table Pointer (TBLPTRL and TBLPTRH)

File registers TBLPTRL and TBLPTRH form a 16-bit pointer to address the 64K program memory space. The table pointer is used by instructions TABLWT and TABLRD.

The TABLRD and the TABLWT instructions allow transfer of data between program and data space. The table pointer serves as the 16-bit address of the data word within the program memory. For a more complete description of these registers and the operation of Table Reads and Table Writes, see Section 7.0.

## 6.6 Table Latch (TBLATH, TBLATL)

The table latch (TBLAT) is a 16-bit register, with TBLATH and TBLATL referring to the high and low bytes of the register. It is not mapped into data or program memory. The table latch is used as a temporary holding latch during data transfer between program and data memory (see descriptions of instructions TABLRD, TABLWT, TLRD and TLWT). For a more complete description of these registers and the operation of Table Reads and Table Writes, see Section 7.0.

FIGURE 7-3: TLRD INSTRUCTION OPERATION

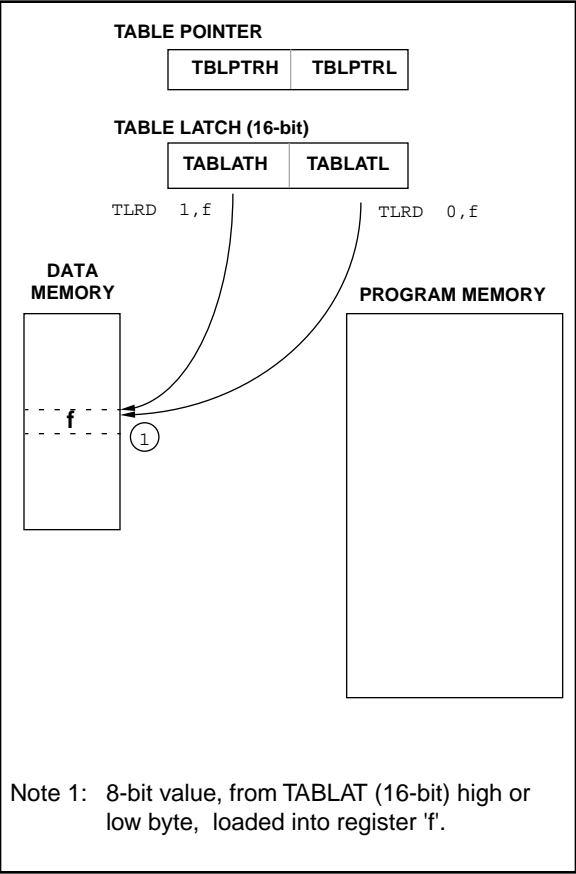
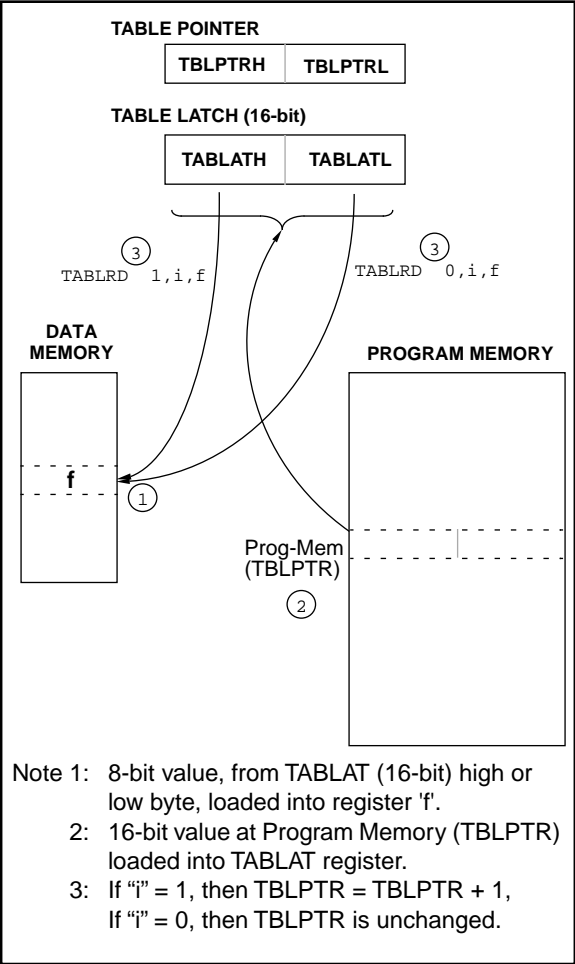


FIGURE 7-4: TABLRD INSTRUCTION OPERATION



## 14.1 Configuration Bits

The PIC17CXX has up to seven configuration locations (Table 14-1). These locations can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. Any write to a configuration location, regardless of the data, will program that configuration bit. A `TABLWT` instruction is required to write to program memory locations. The configuration bits can be read by using the `TABLRD` instructions. Reading any configuration location between FE00h and FE07h will read the low byte of the configuration word (Figure 14-1) into the TABLATL register. The TABLATL register will be FFh. Reading a configuration location between FE08h and FE0Fh will read the high byte of the configuration word into the TABLATL register. The TABLATL register will be FFh.

Addresses FE00h through FE0Fh are only in the program memory space for microcontroller and code protected microcontroller modes. A device programmer will be able to read the configuration word in any processor mode. See programming specifications for more detail.

**TABLE 14-1: CONFIGURATION LOCATIONS**

Bit	Address
FOSC0	FE00h
FOSC1	FE01h
WDTPS0	FE02h
WDTPS1	FE03h
PM0	FE04h
PM1	FE06h
PM2 <sup>(1)</sup>	FE0Fh <sup>(1)</sup>

Note 1: This location does not exist on the PIC17C42.

**Note:** When programming the desired configuration locations, they must be programmed in ascending order. Starting with address FE00h.

## 14.2 Oscillator Configurations

### 14.2.1 OSCILLATOR TYPES

The PIC17CXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1:FOSC0) to select one of these four modes:

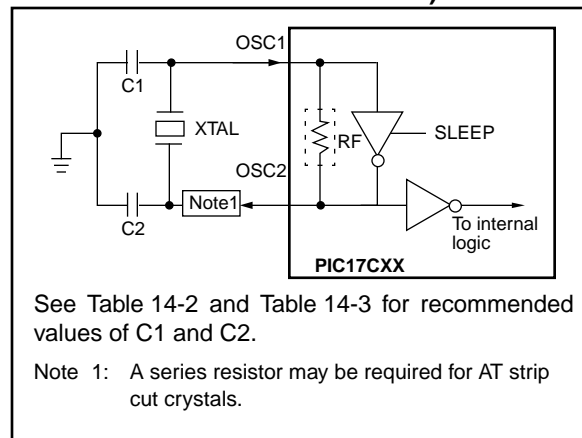
- LF: Low Power Crystal
- XT: Crystal/Resonator
- EC: External Clock Input
- RC: Resistor/Capacitor

### 14.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

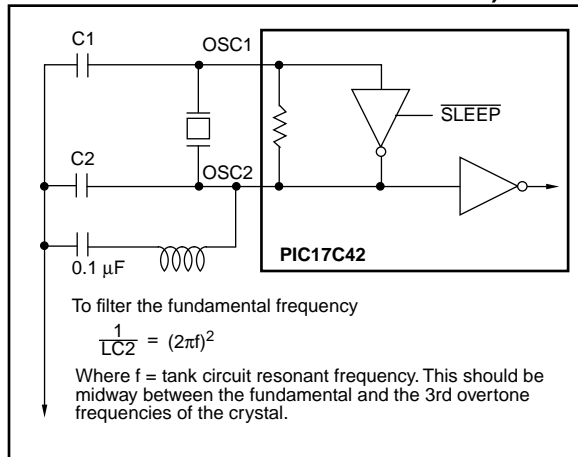
In XT or LF modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 14-2). The PIC17CXX Oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications.

For frequencies above 20 MHz, it is common for the crystal to be an overtone mode crystal. Use of overtone mode crystals require a tank circuit to attenuate the gain at the fundamental frequency. Figure 14-3 shows an example of this.

**FIGURE 14-2: CRYSTAL OR CERAMIC RESONATOR OPERATION (XT OR LF OSC CONFIGURATION)**



**FIGURE 14-3: CRYSTAL OPERATION, OVERTONE CRYSTALS (XT OSC CONFIGURATION)**



**TABLE 14-2: CAPACITOR SELECTION FOR CERAMIC RESONATORS**

Oscillator Type	Resonator Frequency	Capacitor Range C1 = C2
LF	455 kHz	15 - 68 pF
	2.0 MHz	10 - 33 pF
XT	4.0 MHz	22 - 68 pF
	8.0 MHz	33 - 100 pF
	16.0 MHz	33 - 100 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

**Resonators Used:**

455 kHz	Panasonic EFO-A455K04B	± 0.3%
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%

Resonators used did not have built-in capacitors.

**TABLE 14-3: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR**

Osc Type	Freq	C1	C2
LF	32 kHz <sup>(1)</sup>	100-150 pF	100-150 pF
	1 MHz	10-33 pF	10-33 pF
	2 MHz	10-33 pF	10-33 pF
XT	2 MHz	47-100 pF	47-100 pF
	4 MHz	15-68 pF	15-68 pF
	8 MHz <sup>(2)</sup>	15-47 pF	15-47 pF
	16 MHz	TBD	TBD
	25 MHz	15-47 pF	15-47 pF
	32 MHz <sup>(3)</sup>	0 <sup>(3)</sup>	0 <sup>(3)</sup>

Higher capacitance increases the stability of the oscillator but also increases the start-up time and the oscillator current. These values are for design guidance only. Rs may be required in XT mode to avoid overdriving the crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values for external components.

Note 1: For VDD > 4.5V, C1 = C2 ≈ 30 pF is recommended.

2: Rs of 330Ω is required for a capacitor combination of 15/15 pF.

3: Only the capacitance of the board was present.

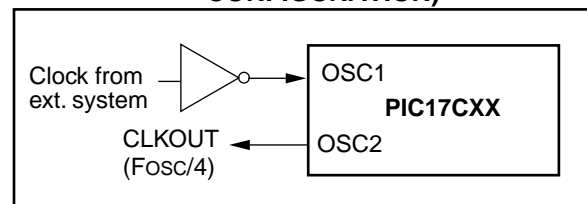
#### Crystals Used:

32.768 kHz	Epson C-001R32.768K-A	± 20 PPM
1.0 MHz	ECS-10-13-1	± 50 PPM
2.0 MHz	ECS-20-20-1	± 50 PPM
4.0 MHz	ECS-40-20-1	± 50 PPM
8.0 MHz	ECS ECS-80-S-4 ECS-80-18-1	± 50 PPM
16.0 MHz	ECS-160-20-1	TBD
25 MHz	CTS CTS25M	± 50 PPM
32 MHz	CRYSTEK HF-2	± 50 PPM

#### 14.2.3 EXTERNAL CLOCK OSCILLATOR

In the EC oscillator mode, the OSC1 input can be driven by CMOS drivers. In this mode, the OSC1/CLKIN pin is hi-impedance and the OSC2/CLKOUT pin is the CLKOUT output (4 TOSC).

**FIGURE 14-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)**



ANDWF

AND WREG with f

Syntax:

[ /label ] ANDWF f,d

Operands:

$0 \leq f \leq 255$

$d \in [0,1]$

Operation:

(WREG) .AND. (f) → (dest)

Status Affected:

Z

Encoding:

0000	101d	ffff	ffff
------	------	------	------

Description:

The contents of WREG are AND'ed with register 'f'. If 'd' is 0 the result is stored in WREG. If 'd' is 1 the result is stored back in register 'f'.

Words:

1

Cycles:

1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: ANDWF REG, 1

Before Instruction  
WREG = 0x17  
REG = 0xC2  
After Instruction  
WREG = 0x17  
REG = 0x02

BCF

Bit Clear f

Syntax:

[ /label ] BCF f,b

Operands:

$0 \leq f \leq 255$

$0 \leq b \leq 7$

Operation:

$0 \rightarrow (f<b>)$

Status Affected:

None

Encoding:

1000	1bbb	ffff	ffff
------	------	------	------

Description:

Bit 'b' in register 'f' is cleared.

Words:

1

Cycles:

1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register 'f'

Example: BCF FLAG\_REG, 7

Before Instruction  
FLAG\_REG = 0xC7  
After Instruction  
FLAG\_REG = 0x47



---

Operands:           None

Operation:

- 00h → WDT
- 0 → WDT postscaler,
- 1 →  $\overline{TO}$
- 1 →  $\overline{PD}$

Status Affected:  $\overline{TO}$ ,  $\overline{PD}$

Encoding:	0000	0000	0000	0100
-----------	------	------	------	------

**Description:** CLRWDT instruction resets the watchdog timer. It also resets the prescaler of the WDT. Status bits  $\overline{TO}$  and  $\overline{PD}$  are set.

Cycles: 1

Q Cycle Activity:

Example: CLRWDT

WDT counter = ?

```
WDT counter      = 0x00
```

WDT Postscaler = 0

$$\overline{TO} = 1$$
$$\overline{PD} = 1$$

Operands:  $0 \leq f \leq 255$

 $d \in [0,1]$ 

Operation:  $(\bar{f}) \rightarrow (\text{dest})$

Status Affected: Z

Encoding:	0001	001d	ffff	ffff
-----------	------	------	------	------

Words: 1

Cycles: 1

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register 'f'

Before Instruction

REG1 = 0x13

### After Instruction

REG1 = 0x13

```
WREG    =    0xEC
```

## DECF Decrement f

Syntax: [ *label* ] DECF f,d

Operands:  $0 \leq f \leq 255$   
 $d \in [0,1]$

Operation:  $(f) - 1 \rightarrow (\text{dest})$

Status Affected: OV, C, DC, Z

Encoding: 

0000	011d	ffff	ffff
------	------	------	------

Description: Decrement register 'f'. If 'd' is 0 the result is stored in WREG. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: DECF CNT, 1

Before Instruction

CNT = 0x01  
Z = 0

After Instruction

CNT = 0x00  
Z = 1

## DECFSZ Decrement f, skip if 0

Syntax: [ *label* ] DECFSZ f,d

Operands:  $0 \leq f \leq 255$   
 $d \in [0,1]$

Operation:  $(f) - 1 \rightarrow (\text{dest})$ ;  
skip if result = 0

Status Affected: None

Encoding: 

0001	011d	ffff	ffff
------	------	------	------

Description: The contents of register 'f' are decremented. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.

If the result is 0, the next instruction, which is already fetched, is discarded, and an NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: HERE DECFSZ CNT, 1  
GOTO LOOP

CONTINUE

Before Instruction

PC = Address (HERE)

After Instruction

CNT = CNT - 1  
If CNT = 0;  
PC = Address (CONTINUE)  
If CNT  $\neq$  0;  
PC = Address (HERE+1)

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## RETURN Return from Subroutine

Syntax: [ *label* ] RETURN

Operands: None

Operation: TOS → PC;

Status Affected: None

Encoding: 

0000	0000	0000	0010
------	------	------	------

Description: Return from subroutine. The stack is popped and the top of the stack (TOS) is loaded into the program counter.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register PCL*	Execute	NOP
Forced NOP	NOP	Execute	NOP

\* Remember reading PCL causes PCLATH to be updated. This will be the high address of where the RETURN instruction is located.

**Example:** RETURN

After Interrupt  
PC = TOS

## RLCF Rotate Left f through Carry

Syntax: [ *label* ] RLCF f,d

Operands:  $0 \leq f \leq 255$   
 $d \in [0,1]$

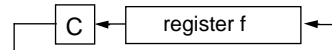
Operation:  $f\langle n \rangle \rightarrow d\langle n+1 \rangle$ ;  
 $f\langle 7 \rangle \rightarrow C$ ;  
 $C \rightarrow d\langle 0 \rangle$

Status Affected: C

Encoding: 

0001	101d	ffff	ffff
------	------	------	------

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

**Example:** RLCF REG, 0

Before Instruction

REG = 1110 0110  
C = 0

After Instruction

REG = 1110 0110  
WREG = 1100 1100  
C = 1

## TLWT Table Latch Write

**Syntax:** [ *label* ] TLWT *t*,*f*

**Operands:**  $0 \leq f \leq 255$   
 $t \in [0,1]$

**Operation:** If  $t = 0$ ,  
 $f \rightarrow \text{TBLATL}$ ;  
 If  $t = 1$ ,  
 $f \rightarrow \text{TBLATH}$

**Status Affected:** None

**Encoding:**

1010	01tx	ffff	ffff
------	------	------	------

**Description:** Data from file register 'f' is written into the 16-bit table latch (TBLAT).  
 If  $t = 1$ ; high byte is written  
 If  $t = 0$ ; low byte is written  
 This instruction is used in conjunction with TABLWT to transfer data from data memory to program memory.

**Words:** 1

**Cycles:** 1

**Q Cycle Activity:**

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register TBLATH or TBLATL

**Example:** TLWT *t*, RAM

**Before Instruction**

*t* = 0  
 RAM = 0xB7  
 TBLAT = 0x0000 (TBLATH = 0x00)  
 (TBLATL = 0x00)

**After Instruction**

RAM = 0xB7  
 TBLAT = 0x00B7 (TBLATH = 0x00)  
 (TBLATL = 0xB7)

**Before Instruction**

*t* = 1  
 RAM = 0xB7  
 TBLAT = 0x0000 (TBLATH = 0x00)  
 (TBLATL = 0x00)

**After Instruction**

RAM = 0xB7  
 TBLAT = 0xB700 (TBLATH = 0xB7)  
 (TBLATL = 0x00)

## TSTFSZ Test f, skip if 0

**Syntax:** [ *label* ] TSTFSZ *f*

**Operands:**  $0 \leq f \leq 255$

**Operation:** skip if  $f = 0$

**Status Affected:** None

**Encoding:**

0011	0011	ffff	ffff
------	------	------	------

**Description:** If 'f' = 0, the next instruction, fetched during the current instruction execution, is discarded and an NOP is executed making this a two-cycle instruction.

**Words:** 1

**Cycles:** 1 (2)

**Q Cycle Activity:**

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	NOP

**If skip:**

Q1	Q2	Q3	Q4
Forced NOP	NOP	Execute	NOP

**Example:** HERE TSTFSZ CNT  
 NZERO :  
 ZERO :

**Before Instruction**

PC = Address(HERE)

**After Instruction**

If CNT = 0x00,  
 PC = Address ( ZERO )  
 If CNT  $\neq$  0x00,  
 PC = Address ( NZERO )

Applicable Devices	42	R42	42A	43	R43	44
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FIGURE 17-11: MEMORY INTERFACE WRITE TIMING

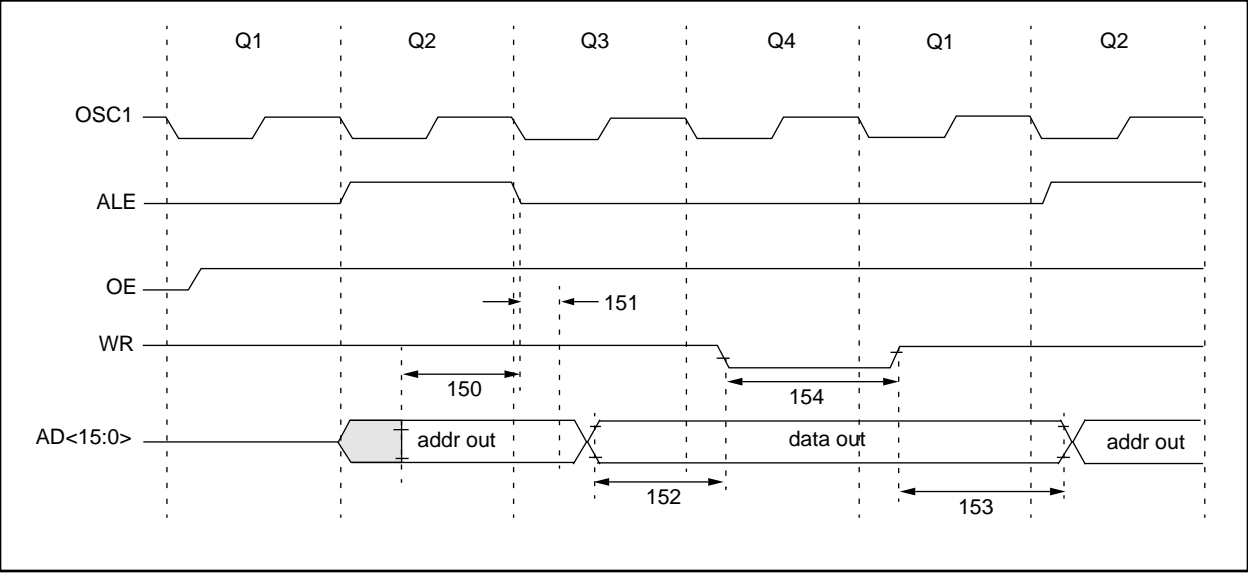
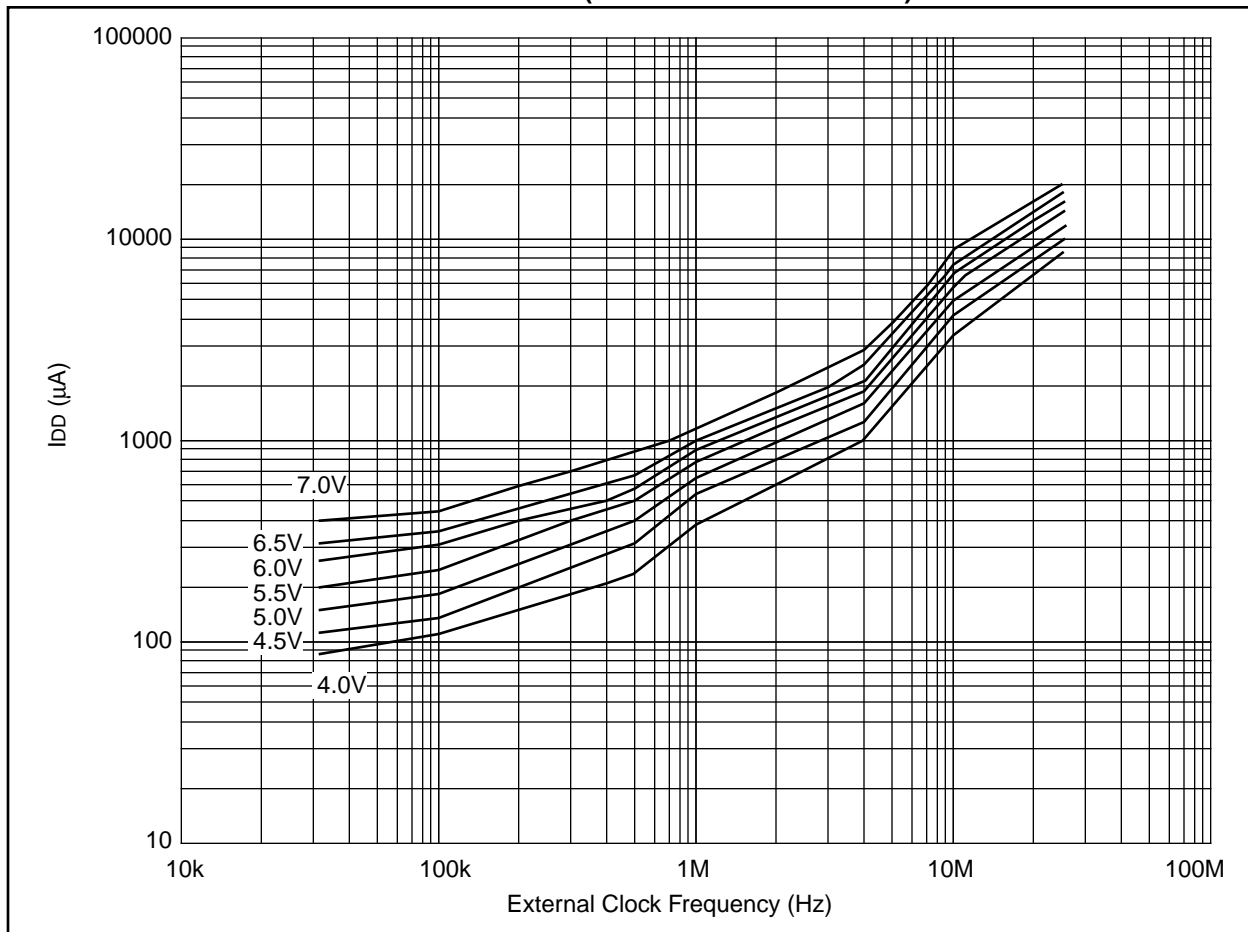


TABLE 17-11: MEMORY INTERFACE WRITE REQUIREMENTS

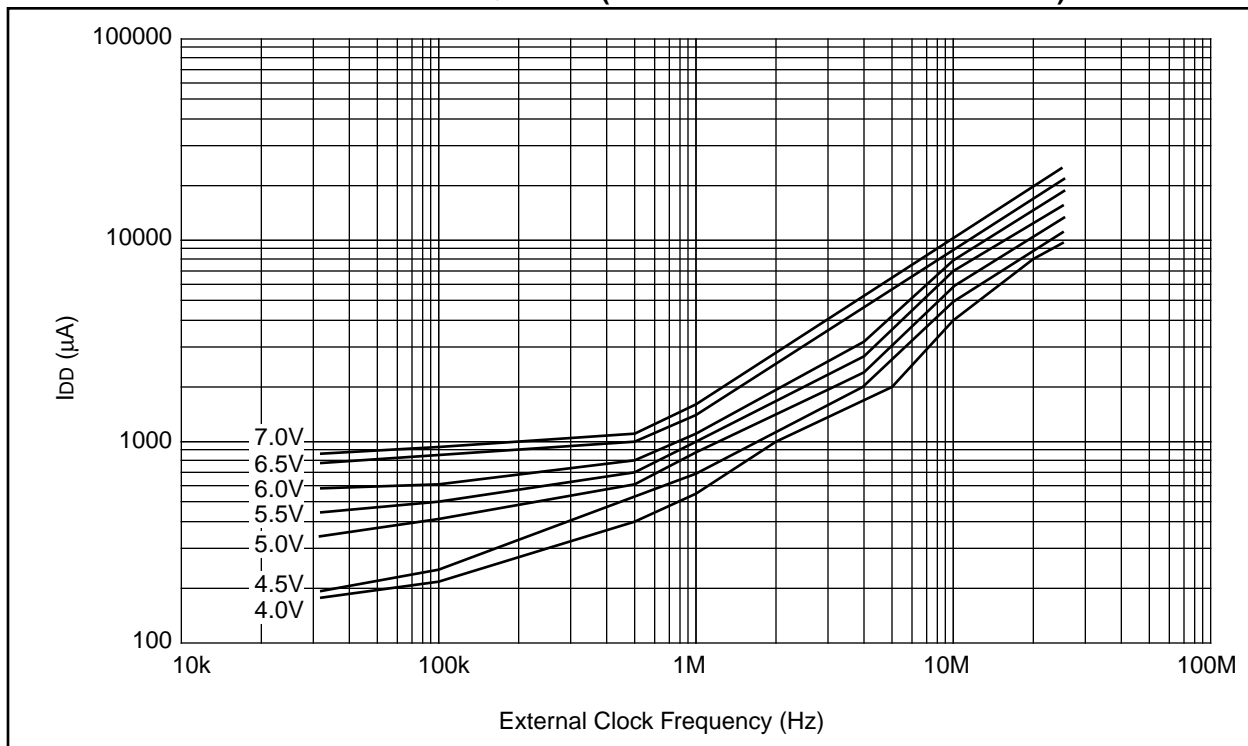
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2aLL	AD<15:0> (address) valid to ALE↓ (address setup time)	0.25Tcy - 30	—	—	ns	
151	TaLL2adl	ALE↓ to address out invalid (address hold time)	0	—	—	ns	
152	TadV2wrL	Data out valid to WR↓ (data setup time)	0.25Tcy - 40	—	—	ns	
153	TwrH2adl	WR↑ to data out invalid (data hold time)	—	0.25Tcy §	—	ns	
154	TwrL	WR pulse width	—	0.25Tcy §	—	ns	

\* These parameters are characterized but not tested.  
† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.  
§ This specification is guaranteed by design.

**FIGURE 18-7: TYPICAL  $I_{DD}$  vs. FREQUENCY (EXTERNAL CLOCK 25°C)**



**FIGURE 18-8: MAXIMUM  $I_{DD}$  vs. FREQUENCY (EXTERNAL CLOCK 125°C TO -40°C)**



# PIC17C4X

Applicable Devices 42 R42 42A 43 R43 44

FIGURE 18-9: TYPICAL  $I_{PD}$  vs.  $V_{DD}$  WATCHDOG DISABLED 25°C

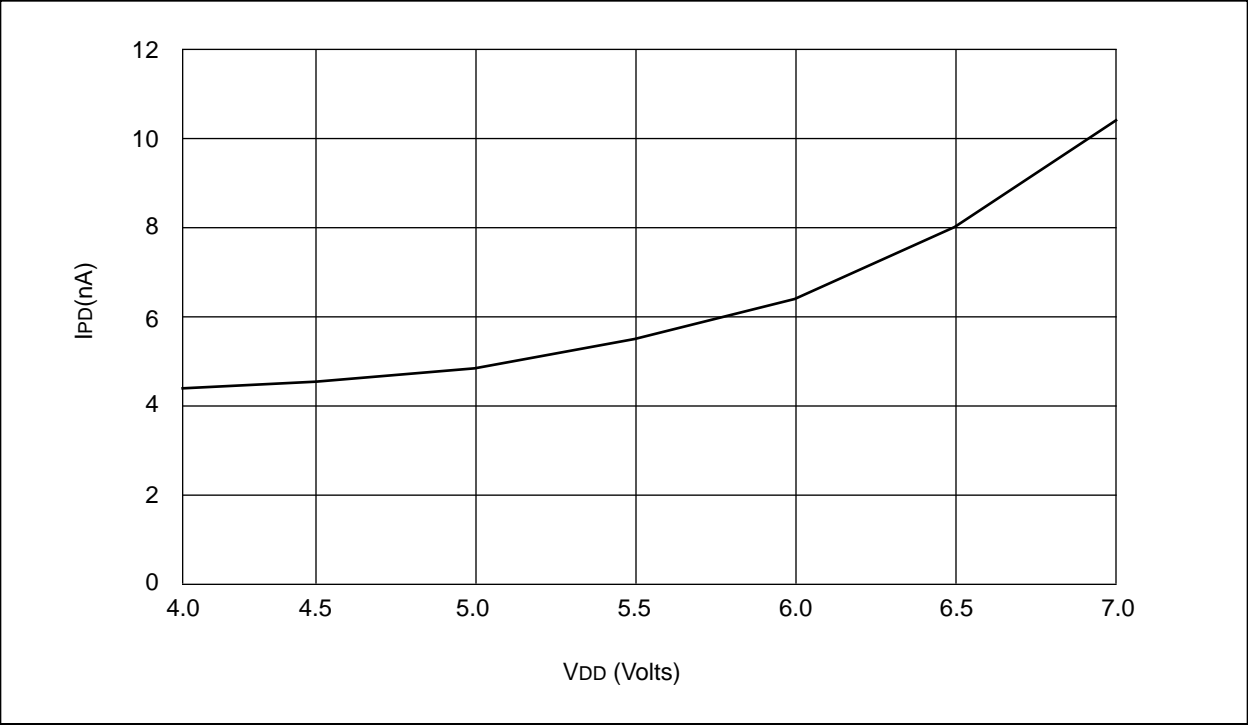
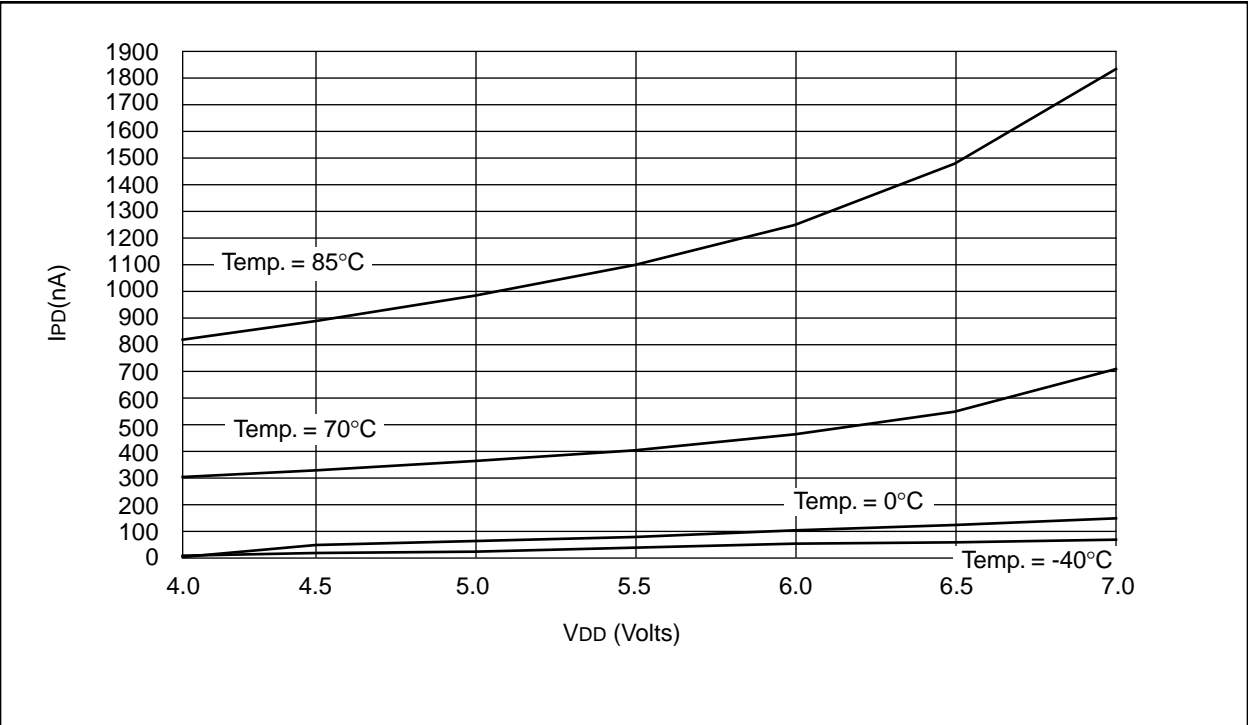
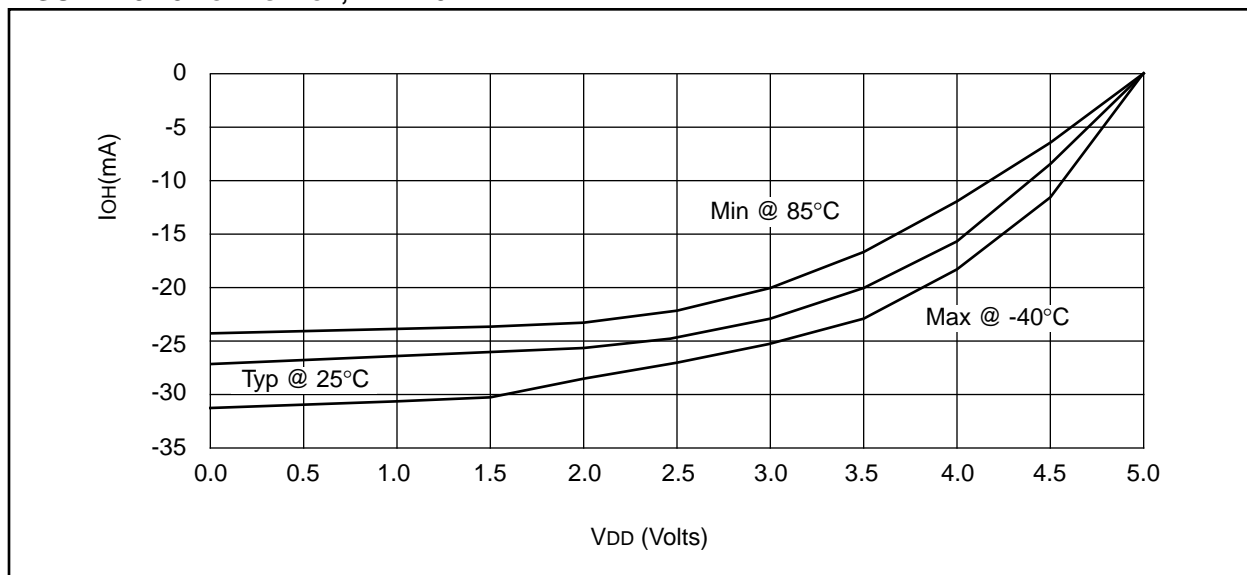


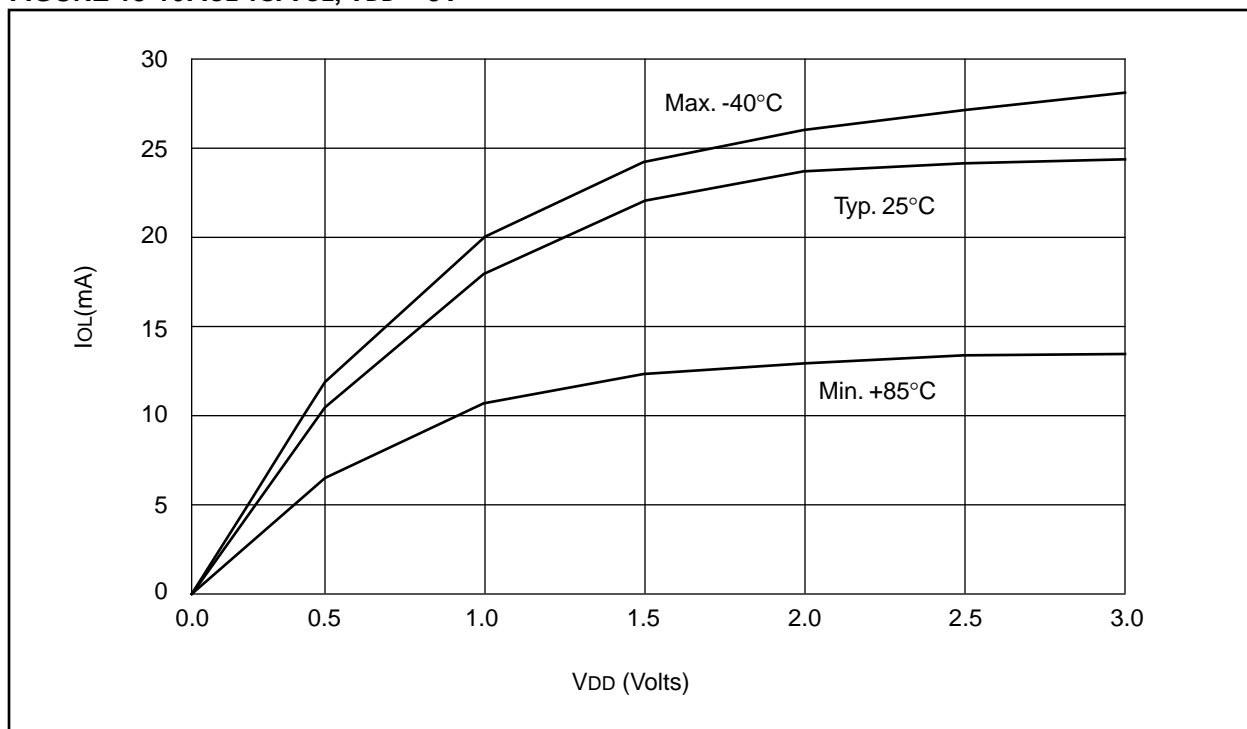
FIGURE 18-10: MAXIMUM  $I_{PD}$  vs.  $V_{DD}$  WATCHDOG DISABLED



**FIGURE 18-15:  $I_{OH}$  vs.  $V_{OH}$ ,  $V_{DD} = 5V$**



**FIGURE 18-16:  $I_{OL}$  vs.  $V_{OL}$ ,  $V_{DD} = 3V$**





Applicable Devices	42	R42	42A	43	R43	44
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DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated)					
		Operating temperature					
		-40°C ≤ TA ≤ +40°C					
		Operating voltage VDD range as described in Section 19.1					
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
		<b>Internal Program Memory Programming Specs (Note 4)</b>					
D110	VPP	Voltage on $\overline{\text{MCLR}}$ /VPP pin	12.75	–	13.25	V	Note 5
D111	VDDP	Supply voltage during programming	4.75	5.0	5.25	V	
D112	IPP	Current into $\overline{\text{MCLR}}$ /VPP pin	–	25 ‡	50 ‡	mA	
D113	IDDP	Supply current during programming	–	–	30 ‡	mA	
D114	TPROG	Programming pulse width	10	100	1000	μs	Terminated via internal/external interrupt or a reset

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the  $\overline{\text{MCLR}}$  pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The  $\overline{\text{MCLR}}$ /VPP pin may be kept in this range at times other than programming, but is not recommended.

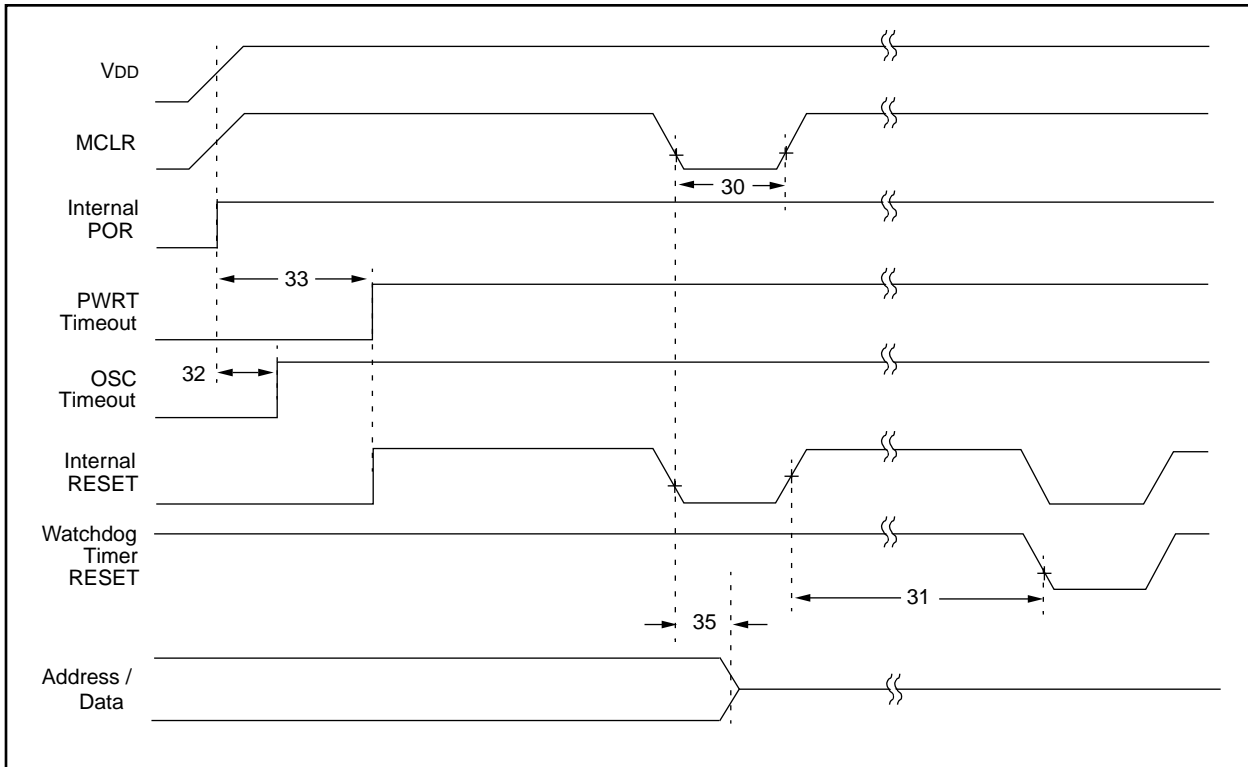
6: For TTL buffers, the better of the two specifications may be used.

**Note:** When using the Table Write for internal programming, the device temperature must be less than 40°C.

# PIC17C4X

Applicable Devices 42 R42 42A 43 R43 44

**FIGURE 19-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, AND POWER-UP TIMER TIMING**



**TABLE 19-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS**

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	Tmcl	MCLR Pulse Width (low)	100 *	—	—	ns	VDD = 5V
31	Twdt	Watchdog Timer Time-out Period (Prescale = 1)	5 *	12	25 *	ms	VDD = 5V
32	Tost	Oscillation Start-up Timer Period	—	1024Tosc§	—	ms	Tosc = OSC1 period
33	Tpwrt	Power-up Timer Period	40 *	96	200 *	ms	VDD = 5V
35	Tmcl2adl	MCLR to System Interface bus (AD15:AD0>) invalid					
		PIC17CR42/42A/43/R43/44	—	—	100 *	ns	
		PIC17LCR42/42A/43/R43/44	—	—	120 *	ns	

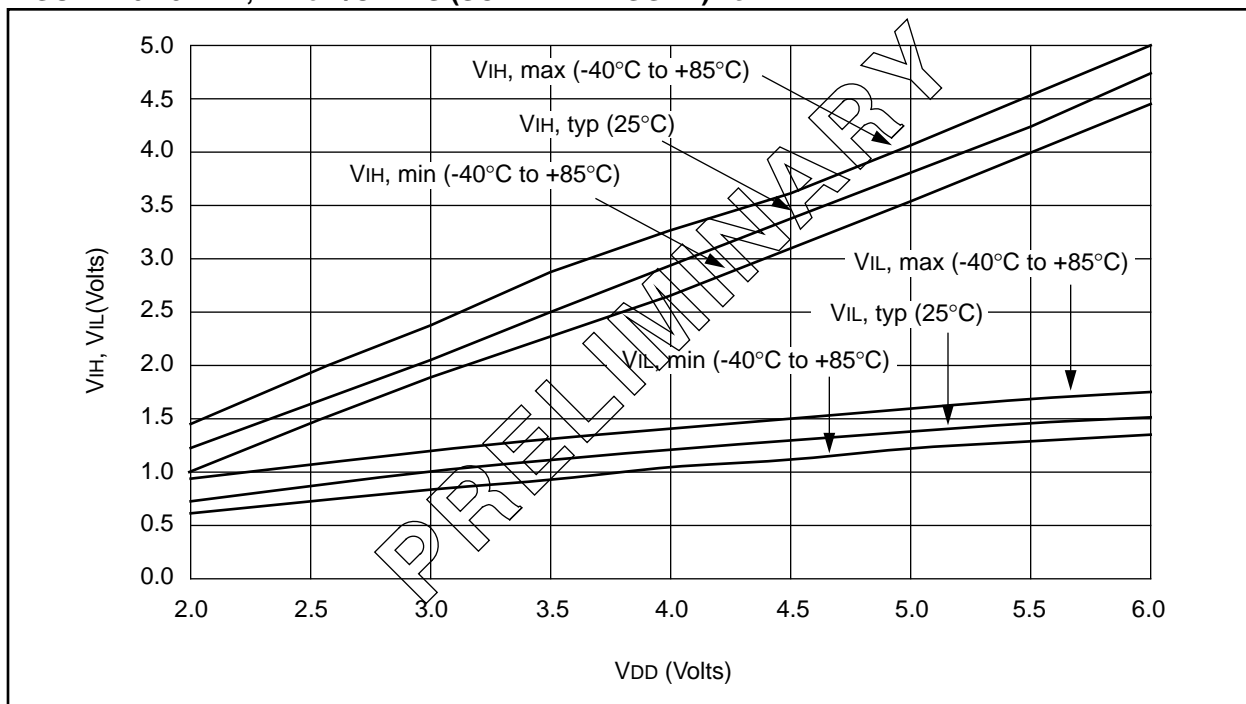
\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

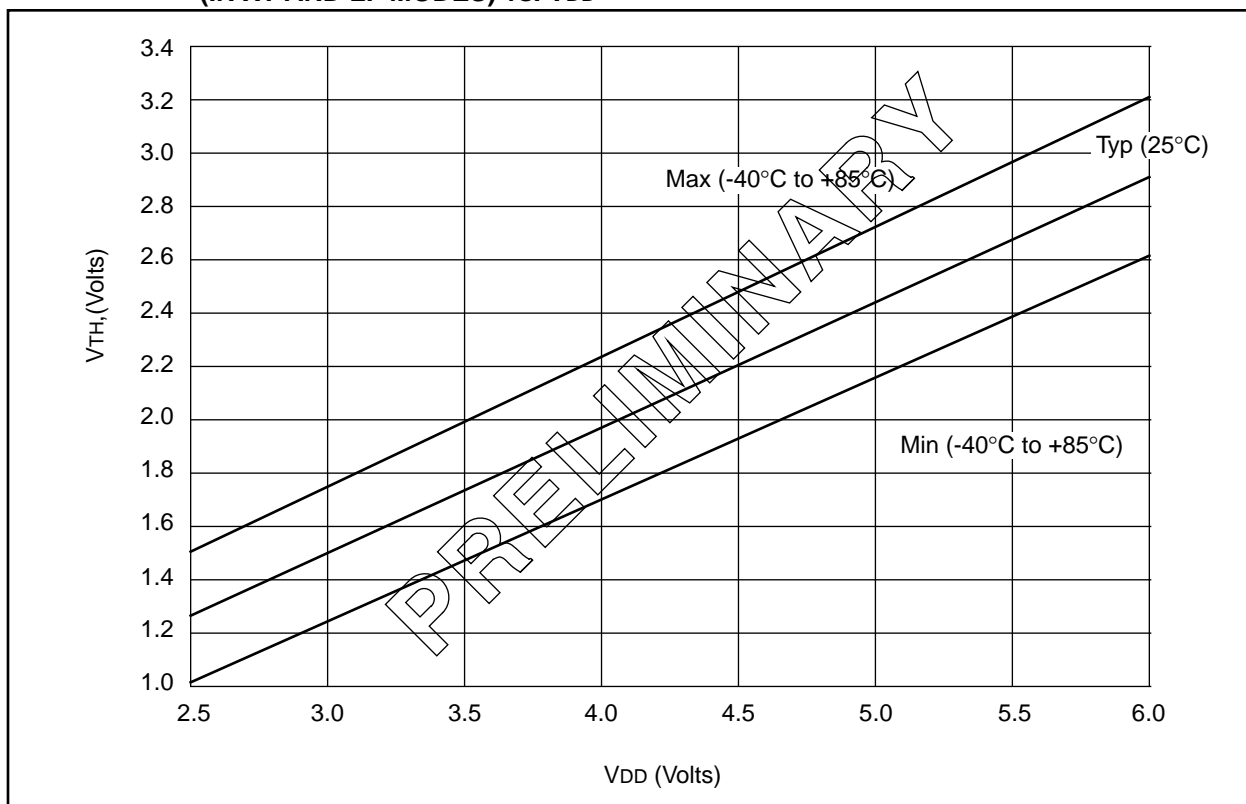
‡ These parameters are for design guidance only and are not tested, nor characterized.

§ This specification ensured by design.

**FIGURE 20-19:  $V_{IH}$ ,  $V_{IL}$  of I/O PINS (SCHMITT TRIGGER) vs.  $V_{DD}$**



**FIGURE 20-20:  $V_{TH}$  (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (IN XT AND LF MODES) vs.  $V_{DD}$**





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